

Faculty Position in Joining and Welding Research Institute, Osaka University

Outline	We are now inviting applications for professor position (Full-time) at Department of Laser Materials Processing under Division of Materials Joining Process in Joining and Welding Research Institute, Osaka University. This department deals with the physics and chemistry of generation, control and irradiation of laser as an energy source for joining and welding in conjunction with manufacturing and fabrication. Applicants should conduct the research and education to develop an advanced technology of laser materials processing on the basis of interaction between light and matter, which leads to an innovation of joining, welding, cutting, surface modification and removal processes. With these researches and education, applicants should contribute to the progress of joining and welding science.
1. Position	Professor (Full-time)
2. Number of Positions	One
3. Affiliation	Joining and Welding Research Institute
4. Working Location	Suita Campus (11-1 Mihogaoka, Ibaraki, Osaka)
5. Specialized Field	Department of Laser Materials Processing, Division of Materials Joining Process
6. Job Description	Research and educational activities in laser materials processing (For students in master's course and doctor's course)
7. Qualifications	Ph.D. or equivalent in related field/s is required.
8. Commencement Date	As soon as possible
9. Term of Employment	No Fixed Term
10. Employment	Discretionary Labor System, Special Work Type *Based on the 'Regulations Pertaining to Working Hours, Holidays and Leave for National University Corporation Osaka University Staff.' http://www.osaka-u.ac.jp/en/guide/information/joho/files/06.pdf
11. Salary and Benefits	*Based on the 'Salary Regulations for National University Corporation Osaka University Staff.' http://www.osaka-u.ac.jp/en/guide/information/joho/files/10.pdf
12. Insurance	Successful candidate will join National Public Service Personnel Mutual Aid Associations, Employment Insurance and Workers' Accident Compensation Insurance

13. Application Documents	<p>Applications should be written in English or Japanese.</p> <ol style="list-style-type: none"> 1. Curriculum Vitae (photo attached) *Please use the university form available at following website. http://www.osaka-u.ac.jp/en/news/employ/en/news/employ/academic_staff/index.html 2. List of research achievements and academic publications (Please classify publications into categories such as refereed original paper, international conference paper, book, review paper, tutorial paper, patent and so on. The refereed original papers should include the journal impact factor and the total number of citations.) 3. Copies of 5 major original papers (Photocopies acceptable) 4. Major research projects and their achievements (A4, 2 page limit) 5. Research plan and statement of educational aspirations (A4, 2 page limit) 6. The acquirement of external research funds 7. Name and outline of prizes and awards 8. Recommendation letters from two referees (unaccompanied or under separate cover), or Names and contact information of two referees
14. Contacts	<p>(By postal mail) Kazuhisa Yamasaki (Mr.) General Affairs Division, Joining and Welding Research Institute, Osaka University 11-1 Mihogaoka, Ibaraki, Osaka 567-0047, JAPAN</p> <p>*Write 'Application for faculty position (Professor(Full-time)) in Department of Laser Materials Processing, Division of Materials Joining process' on the envelope in red ink.</p> <p>*Send application documents by registered mail.</p> <p>*Submitted application documents will not be returned.</p> <p>*Submitted application documents will only be used for the purpose of application screening and hiring procedure.</p> <p>Contact Person: Professor Manabu Tanaka, Director of JWRI Tel: +81-6-6879-8640 E-mail: tanaka@jwri.osaka-u.ac.jp</p>
15. Application deadline	October 30th, 2016. (Japan time).
16. Selection Process	<p>After documents have been reviewed, only shortlisted candidates will be interviewed if necessary.</p> <p>*Shortlisted candidates will be notified. Please note that unsuccessful applicants after initial screening will not be contacted.</p> <p>*Travel and accommodation fees necessary for interviews are to be covered by the applicant.</p>
17. Additional Information	<p>Please refer to 'Work Regulations for National University Corporation Osaka University Staff' and other regulations for work and other related conditions. http://www.osaka-u.ac.jp/en/guide/information/joho/kitei_shugyou.html</p> <p>Information in this document is subject to change. Please confirm details at interview.</p>